

# 5A, 200V - 1000V Fast Recovery Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- General purpose

## **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.250g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	5	Α	
$V_{RRM}$	200 - 1000	V	
I <sub>FSM</sub>	164	Α	
$T_{JMAX}$	150	°C	
Package	DO-214AB (SMC)		
Configuration	Single die		









DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS5D-T	RS5G-T	RS5J-T	RS5K-T	RS5M-T	UNIT
Marking code on the devic	е		RS5D	RS5G	RS5J	RS5K	RS5M	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	140	280	420	560	700	٧
Forward current		I <sub>F</sub>	5					Α
		1	164					Α
		I <sub>FSM</sub>		364			Α	
Junction temperature		T <sub>J</sub> -55 to +150		-55 to +150			°C	
Storage temperature		T <sub>STG</sub>	-55 to +150		°C			

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R <sub>eJL</sub>	25	°C/W	
Junction-to-ambient thermal resistance	R <sub>eJA</sub>	54	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	18	°C/W	

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	RS5D-T RS5G-T	$I_F = 2.5A, T_J = 25^{\circ}C$		0.86	-	V
		$I_F = 5.0A, T_J = 25^{\circ}C$		0.93	1.30	V
		I <sub>F</sub> = 2.5A, T <sub>J</sub> = 125°C		0.72	-	V
		I <sub>F</sub> = 5.0A, T <sub>J</sub> = 125°C		0.79	0.91	V
		I <sub>F</sub> = 2.5A, T <sub>J</sub> = 25°C		0.91	-	V
<b>F</b> (1)	DOELT	$I_F = 5.0A, T_J = 25^{\circ}C$	] ,,	0.98	1.30	V
Forward voltage <sup>(1)</sup>	RS5J-T	I <sub>F</sub> = 2.5A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.77	-	V
		I <sub>F</sub> = 5.0A, T <sub>J</sub> = 125°C		0.85	1.00	V
		$I_F = 2.5A, T_J = 25^{\circ}C$		0.97	-	V
	RS5K-T	$I_F = 5.0A, T_J = 25^{\circ}C$		1.06	1.30	V
	RS5M-T	I <sub>F</sub> = 2.5A, T <sub>J</sub> = 125°C		0.82	-	V
		I <sub>F</sub> = 5.0A, T <sub>J</sub> = 125°C		0.91	1.04	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C		-	10	μΑ
		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	200	μΑ
	RS5D-T RS5G-T	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	-	150	ns
Reverse recovery time	RS5J-T			-	250	ns
	RS5K-T RS5M-T	177 - 0.2071		-	500	ns
	RS5D-T RS5G-T		C₃	57	-	pF
Junction capacitance	RS5J-T	$1MHz, V_R = 4.0V$		46	-	pF
	RS5K-T RS5M-T			31	-	pF

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
RS5x-T	DO-214AB (SMC)	3,000 / Tape & Reel		

## Notes:

1. "x" defines voltage from 200V(RS5D-T) to 1000V(RS5M-T)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

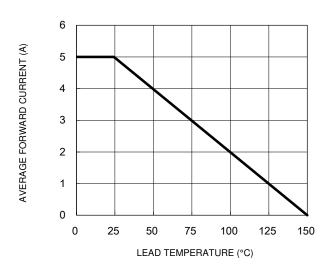


Fig.3 Typical Reverse Characteristics

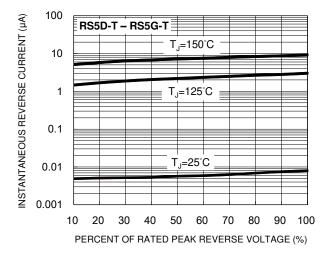


Fig.5 Typical Reverse Characteristics

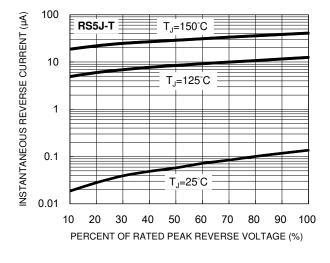


Fig.2 Typical Junction Capacitance

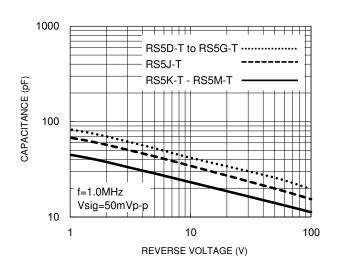
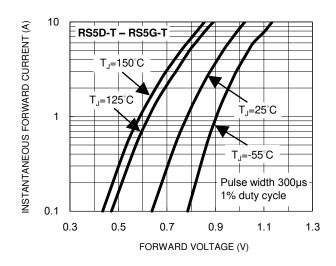
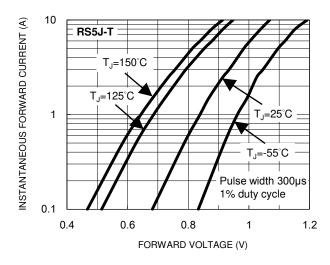


Fig.4 Typical Forward Characteristics



**Fig.6 Typical Forward Characteristics** 





## **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.7 Typical Reverse Characteristics

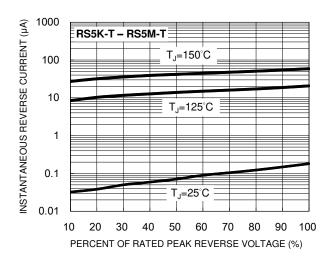


Fig.8 Typical Forward Characteristics

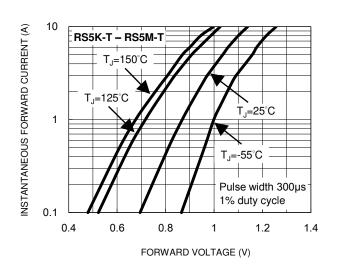
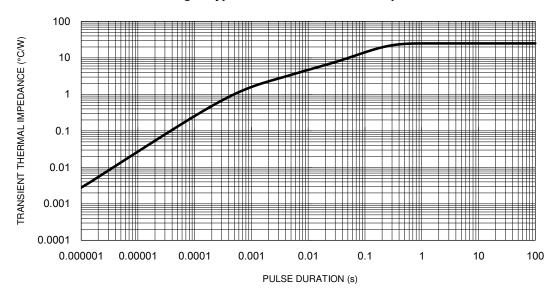
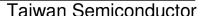


Fig.9 Typical Transient Thermal Impedance

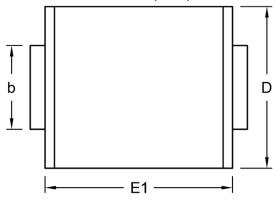


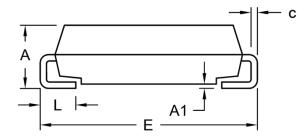




# **PACKAGE OUTLINE DIMENSIONS**

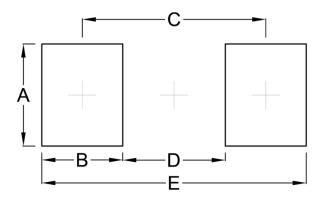
DO-214AB (SMC)





DIM. Unit (		(mm)	Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	1.99	2.61	0.078	0.103
A1	0.10	0.20	0.004	0.008
b	2.85	3.27	0.112	0.129
С	0.15	0.31	0.006	0.012
D	5.59	6.22	0.220	0.245
E	7.75	8.13	0.305	0.320
E1	6.60	7.11	0.260	0.280
L	0.76	1.52	0.030	0.060

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	3.82	0.150
В	3.03	0.119
С	6.87	0.270
D	3.84	0.151
E	9.90	0.390

## **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



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